2SC3981, 2SC3981A

Silicon NPN triple diffusion planar type

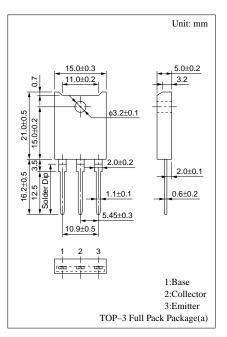
For high breakdown voltage high-speed switching

Features

- High-speed switching
- High collector to base voltage V_{CBO}
- Wide area of safe operation (ASO)
- Satisfactory linearity of foward current transfer ratio h_{FE}
- Full-pack package which can be installed to the heat sink with one screw

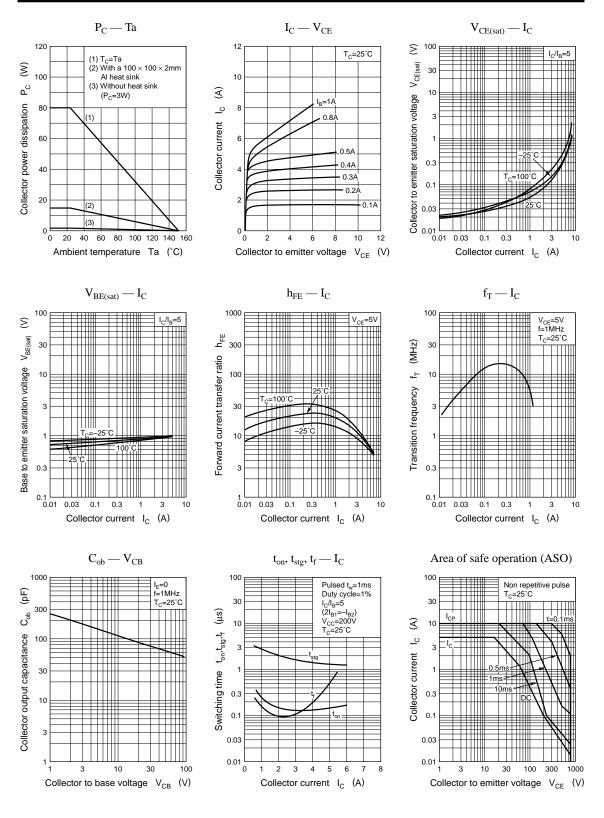
_ _ _ _ _ _ _ _ _ _					
Parameter		Symbol	Ratings	Unit	
Collector to	2SC3981	17	900	V	
base voltage	2SC3981A	V _{CBO}	1000		
Collector to	2SC3981	3.7	900	v	
emitter voltage	2SC3981A	V _{CES}	1000		
Collector to emitter voltage		V _{CEO}	800	V	
Emitter to base voltage		V _{EBO}	7	V	
Peak collector current		I _{CP}	10	А	
Collector current		I _C	5	А	
Base current		I _B	3	А	
Collector power	T _C =25°C	D	80	W	
dissipation	Ta=25°C	P _C	3		
Junction temperature		Tj	150	°C	
Storage temperature		T _{stg}	-55 to +150	°C	
-					

Absolute Maximum Ratings $(T_c=25^{\circ}C)$

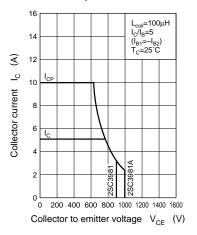


Electrical Characteristics (T_C=25°C)

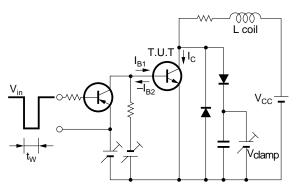
Parameter		Symbol	Conditions	min	typ	max	Unit
Collector cutoff	2SC3981	I _{CBO}	$V_{CB} = 900V, I_E = 0$			50	μA
current	2SC3981A		$V_{CB} = 1000V, I_E = 0$			50	
Emitter cutoff current		I _{EBO}	$V_{EB} = 7V, I_C = 0$			50	μA
Collector to emitter voltage		V _{CEO}	$I_{\rm C} = 10 {\rm mA}, I_{\rm B} = 0$	800			V
Forward current transfer ratio		h _{FE1}	$V_{CE} = 5V, I_{C} = 0.1A$	8			
		h _{FE2}	$V_{CE} = 5V, I_C = 3A$	6			
Collector to emitter saturation voltage		V _{CE(sat)}	$I_{\rm C} = 3A, I_{\rm B} = 0.6A$			1.5	V
Base to emitter saturation voltage		V _{BE(sat)}	$I_{\rm C} = 3A, I_{\rm B} = 0.6A$			1.5	V
Transition frequency		f _T	$V_{CE} = 5V, I_C = 0.5A, f = 1MHz$		15		MHz
Turn-on time		t _{on}	$I_{C} = 3A, I_{B1} = 0.6A, I_{B2} = -1.2A,$ $V_{CC} = 250V$			0.7	μs
Storage time		t _{stg}				2.5	μs
Fall time		t _f				0.3	μs



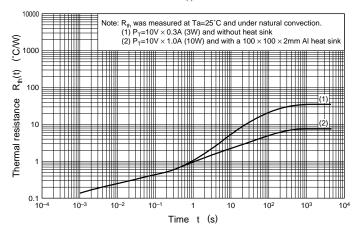
Area of safe operation, reverse bias ASO



Reverse bias ASO measuring circuit



 $R_{th(t)} - t$



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